



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Isabelle Chartier, et al.  
SERIAL NO.: 10/560,405  
FILING DATE: 12/12/2005 CONFIRMATION NO.: 5533  
TITLE: Method of Bonding Microstructured Substrates  
EXAMINER: Jessica Lee Ward  
ART UNIT: 1733

**CERTIFICATE OF MAILING**

I hereby certify that this paper is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Mail Stop Amendment Commissioner for Patents, P.O. Box 1450, Alexandria VA 22313-1450, on the date printed below:

Date: 2/1/08

Name: Michelle R. Crosby

Michelle R. Crosby

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT AND RESPONSE TO OFFICE ACTION**

Dear Sir:

This paper is responsive to the Office Action mailed August 6, 2007. Please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing of claims, which begins on page 2 of this paper.

**Remarks** begin on page 6 of this paper.